

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1. (Previously Presented) A method of forming a fine pattern, comprising the steps of:
  - forming a silicon-oxide-based film over a substrate by using  $\text{SiH}_4$  and  $\text{N}_2\text{O}$  as material gases at a reaction temperature of over 400 °C;
  - forming a chemically-amplified photoresist layer on the silicon-oxide-based film; and
  - transferring a mask pattern onto the chemically-amplified photoresist layer upon exposure through a mask,wherein, in the step of forming the silicon-oxide-based film, a nitrogen content of a surface of the silicon-oxide-based film is made to about a value of 0.01 atm% to 0.08 atm%.
2. (Canceled)
3. (Previously Presented) The method of forming a fine pattern according to claim 1, further comprising a step of
  - exposing the surface of the silicon-oxide-based film to plasma atmosphere of  $\text{O}_2$  or  $\text{N}_2\text{O}$  between the step of forming the silicon-oxide-based film and the step of forming the chemically-amplified photoresist layer.
4. (Canceled)
5. (Previously Presented) A method of manufacturing a semiconductor device, comprising the steps of:
  - forming a silicon-oxide-based film over an underlying layer, wherein the silicon-oxide-based film is formed by using  $\text{SiH}_4$  and  $\text{N}_2\text{O}$  as material gases at a reaction temperature of over 400 °C such that a surface of the silicon-oxide-based film has a nitrogen content of about 0.01 atm% to 0.08 atm%;
  - forming a chemically-amplified photoresist layer on the silicon-oxide-based film;

transferring a mask pattern onto the chemically-amplified photoresist layer upon exposure through a mask; and

etching the underlying layer by way of a resist pattern, to thereby form a fine pattern in the underlying layer.

6. (Previously Presented) The method of forming a fine pattern according to claim 1, wherein the silicon-oxide-based film is deposited by means of a plasma CVD technique.

7. (Canceled).

8. (Previously Presented) The method of forming a fine pattern according to claim 1, wherein the silicon-oxide-based film is formed at a reaction temperature of 450 °C or more.

9. (Currently Amended) The method of ~~forming a fine pattern~~ manufacturing a semiconductor device according to claim 5, wherein the silicon-oxide-based film is formed at a reaction temperature of 450 °C or more.

10. (New) The method of manufacturing a semiconductor device according to claim 5, further comprising a step of:

exposing the surface of the silicon-oxide-based film to plasma atmosphere of O<sub>2</sub> or N<sub>2</sub>O between the step of forming the silicon-oxide-based film and the step of forming the chemically-amplified photoresist layer.